

RQ6E045BN

Nch 30V 4.5A Power MOSFET

Datasheet

V _{DSS}	30V
R _{DS(on)} (Max.)	30mΩ
I _D	±4.5A
P _D	1.25W

Features

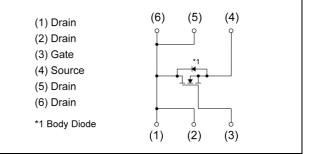
Application

Switching

- 1) Low on resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (TSMT6).
- 4) Pb-free lead plating ; RoHS compliant

● Outline	
SOT-457T	a (0)
SC-95	(6) (5) (4)
TSMT6	

●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Quantity (pcs)	3000
	Taping code	TCR
	Marking	ZQ

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	30	V	
Continuous drain current	۱ _D *1	±4.5	А	
Pulsed drain current	I _{DP} *2	±18	А	
Gate - Source voltage	V _{GSS}	±20	V	
Avalanche current, single pulse	I _{AS} *3	4.5	А	
Avalanche energy, single pulse	E _{AS} *3	1.5	mJ	
Power dissipation	P _D *4	1.25	W	
Junction temperature	Tj	150	°C	
Operating junction and storage temperature range	T _{stg}	-55 to +150	S°	

Thermal resistance

Parameter	Sumbol	Values			Linit
	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R_{thJA}^{*4}	-	100	-	°C/W

•Electrical characteristics (T_a = 25°C)

Deremeter	Currence of	Conditions	Values			Linit	
Parameter	Symbol	mbol Conditions		Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 1mA	30	-	-	V	
Breakdown voltage	reakdown voltage $\Delta V_{(BR)DSS}$ I _D = 1mA		_	21		mV/°C	
temperature coefficient	ΔT_j	referenced to 25°C	-	21	_		
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V	-	-	1	μA	
Gate - Source leakage current	I _{GSS}	V_{GS} = ±20V, V_{DS} = 0V	-	-	±100	nA	
Gate threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 1mA$	1.0	-	2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I _D = 1mA		0	-	mV/°C	
temperature coefficient	ΔT_j	referenced to 25°C	-	-3			
Static drain - source	D *5	V _{GS} = 10V, I _D = 4.5A	-	21	30		
on - state resistance	${\sf R}_{\sf DS(on)}^{*5}$	V _{GS} = 4.5V, I _D = 4.5A	-	35	49	mΩ	
Forward Transfer Admittance	Y _{fs} * ⁵	V _{DS} = 5V, I _D = 4.5A	2.5	-	-	S	

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10µs, Duty cycle \leq 1%

*3 L \simeq 100µH, V_DD = 15V, R_G = 25\Omega, STARTING T_{ch} = 25°C Fig.3-1,3-2

*4 Mounted on a ceramic boad (30×30×0.8mm)

*5 Pulsed



• Electrical characteristics ($T_a = 25^{\circ}C$)

Parameter	Sumbol	Conditions		Unit		
	Symbol Conditions –		Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	330	-	
Output capacitance C_{oss} V_{DS} = 15V		-	55	-	pF	
Reverse transfer capacitance	rse transfer capacitance C _{rss} f = 1MHz		-	45	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 15V, V_{GS} = 10V$	-	6	-	
Rise time	t _r *5	I _D = 2.25A	-	11	-	20
$\label{eq:relation} \begin{tabular}{lllllllllllllllllllllllllllllllllll$		-	12	_	ns	
Fall time	t _f *5	R _G = 10Ω	-	6	-	[

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumbol	Conditi	Conditions		Values		
Parameter Symbol C		Conditi	Jonations		Тур.	Max.	Unit
Total gata charge	rge Q _g *5	V _{DD} ≃ 15V	V _{GS} = 10V	-	8.4	-	
Total gate charge				-	4.7	-	-0
Gate - Source charge	Q_{gs}^{*5}		V _{GS} = 4.5V	-	1.7	-	nC
Gate - Drain charge	Q_{gd}^{*5}			-	1.6	-	

•Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Deremeter	Cumpbed	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I _S *1	T - 25°0	-	-	1.0	А
Pulse forward current	I_{SP}^{*2}	T _a = 25°C	-	-	18	А
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 1.0A	-	-	1.2	V





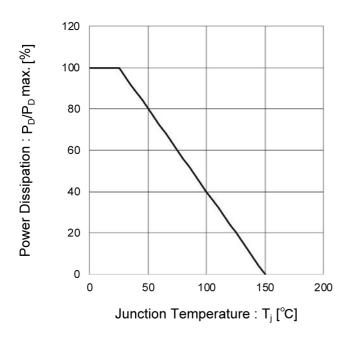


Fig.1 Power Dissipation Derating Curve

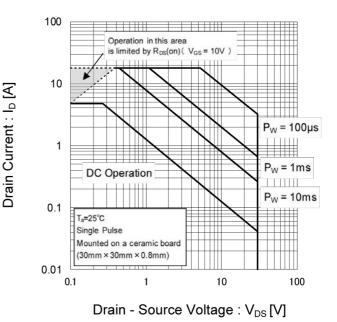
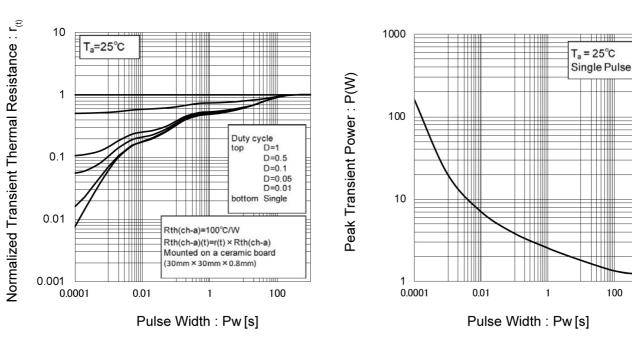


Fig.2 Maximum Safe Operating Area

Fig.3 Normalized Transient Thermal
Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation





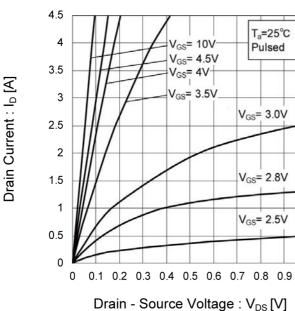


Fig.5 Typical Output Characteristics(I)

V_{GS}= 10V

V_{GS}= 4.5V

V_{GS}= 4V

V_{GS}= 3.5V

T_a=25°C

Pulsed

V_{GS}= 3.0V

V_{GS}= 2.8V

V_{GS}= 2.5V

1

Fig.6 Typical Output Characteristics(II)

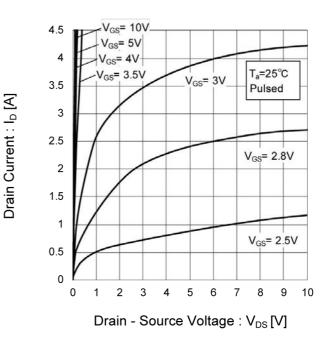
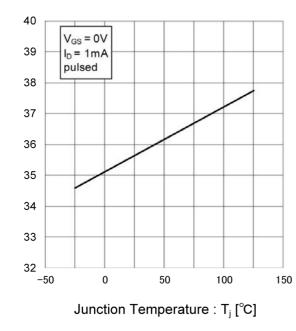


Fig.7 Breakdown Voltage vs. Junction Temperature

Drain-Source Breakdown Voltage : V_{(BR)DSS} [V]





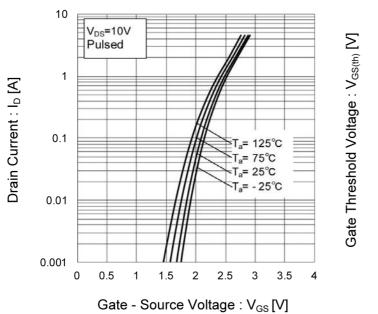


Fig.8 Typical Transfer CharacteristicsFig.9 Gate Three

Fig.9 Gate Threshold Voltage vs. Junction Temperature

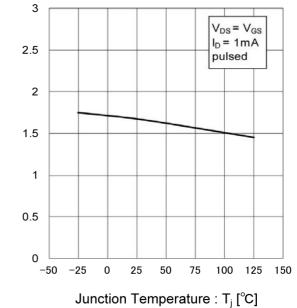
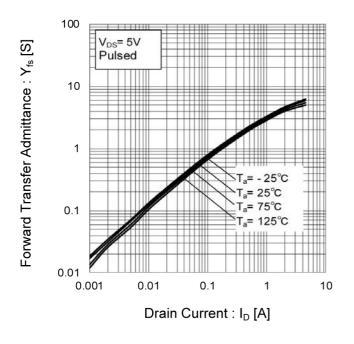


Fig.10 Transconductance vs. Drain Current





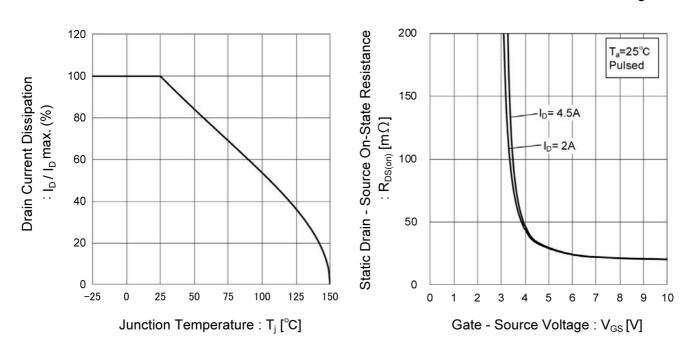
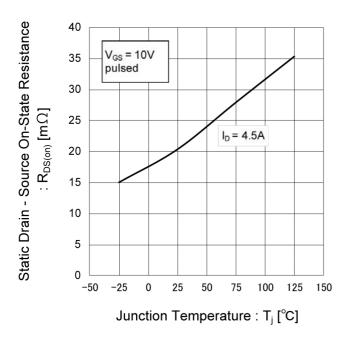


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





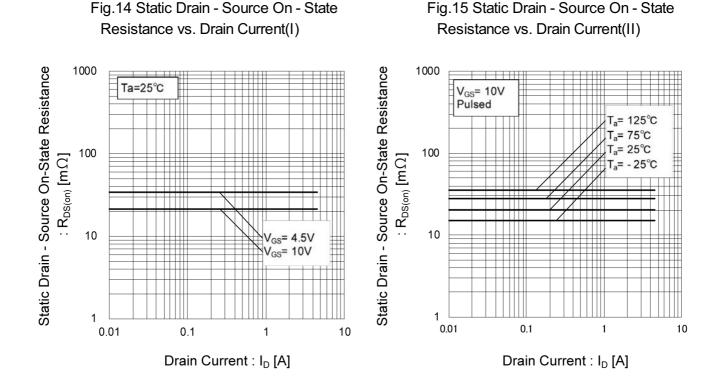
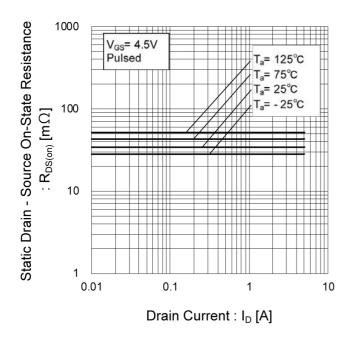


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)





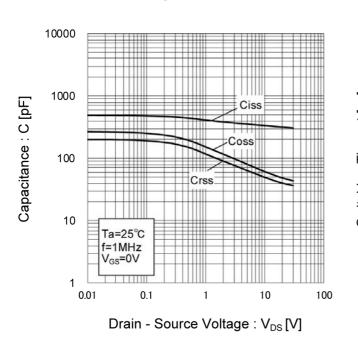


Fig.17 Typical Capacitance vs. Drain -Source Voltage

Fig.18 Switching Characteristics

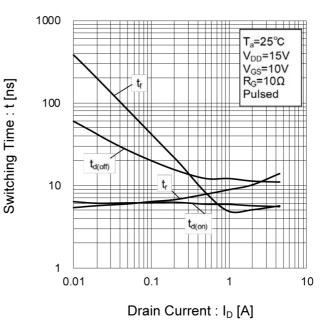


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V_{GS} [V]

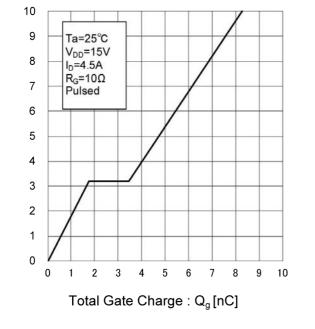
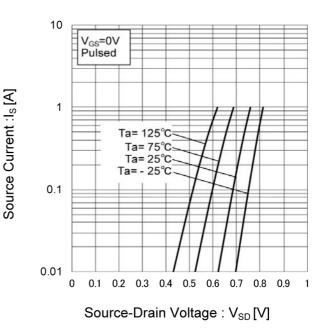


Fig.20 Source Current vs. Source Drain Voltage



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

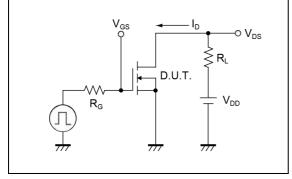


Fig.2-1 Gate Charge Measurement Circuit

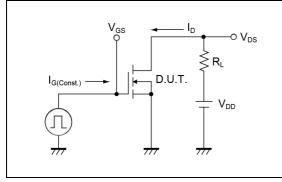


Fig.3-1 AVALANCHE MEASUREMENT CIRCUIT

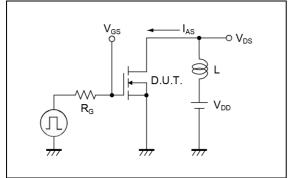


Fig.1-2 Switching Waveforms

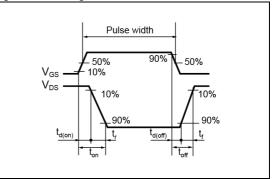


Fig.2-2 Gate Charge Waveform

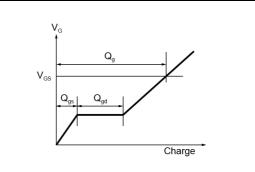
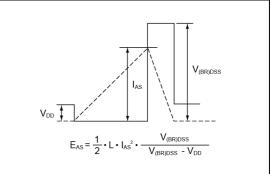


Fig.3-2 AVALANCHE WAVEFORM

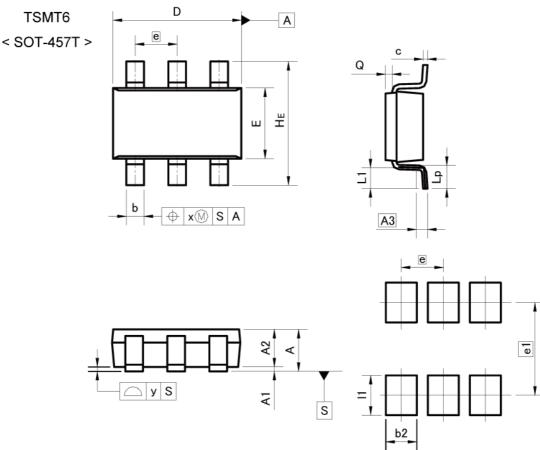


Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	8 4	1.00	-	0.039
A1	0.00	0.10	0.000	0.004
A2	0.75	0.95	0.030	0.037
A3	0.	25	0.0	10
b	0.35	0.50	0.014	0.020
С	0.10	0.26	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.010
x	-	0.20	-	0.008
У	1	0.10	-	0.004
	MILIM	ETERS	INC	HES
DIM -	MIN	MAX	MIN	MAX
b2]	0.70	-	0.028
e1	2.	10	0.0	83

Dimension in mm/inches

-

11



0.90

-



0.035

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ		CLASSⅢ	

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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